

REMARKS

Favorable reconsideration is respectfully requested.

The claims are 1 to 5.

The above amendment is responsive to points set forth in the Official Action.

With regard to Official Action paragraph 1, terminology along the lines suggested by the Examiner is now employed.

With regard to the rejection on indefiniteness in Official Action paragraph 3, the term "highly-elastic" is no longer recited.

Claims 1 to 5 have been rejected under 35 USC 102(b) as anticipated by or, in the alternative, under 35 USC 103(a) as obvious over, Ishii et al. (U.S. 5,368,921).

This rejection is respectfully traversed.

Ishii et al. disclose a metal foil-clad laminate obtained by molding a resin-impregnated glass fabric, and a metal foil, wherein the resin-impregnated substrate contains from 5 to 30 % by weight of an inorganic filler; thereby providing a surface smooth metal foil-glass laminate having a diminished surface undulation attributable to the resin impregnated substrate (see claim 1).

Ishii et al.'s. metal foil-clad laminate having a diminished surface undulation is obtained by using an inorganic filler having a special particle diameter. However, since Ishii et al. use a glass fabric having surface undulation, it is not sufficient to overcome the problem of the surface undulation.

On the contrary, the present invention uses a glass fabric having a special gas permeability, a special thickness and a special weight.

The following table discloses glass fabrics used in the examples and the comparative examples in the present invention:

	Example		Comparative Example		Present Invention
	1	2	1	2	
Gas permeability, $\text{cm}^3/\text{cm}^2/\text{sec.}$	19	3	180	28	1-20
Thickness, μm	40	130	50	100	25-150
Weight, g	27	136	48	105	15-165

Evaluations of the above glass fabrics as a printed wiring board and a semiconductor plastic package are disclosed in Table 1 and 2 of the present specification.

In this regard, distortion and surface roughness of Examples 1 and 2 are superior to those of Comparative Examples 1 and 2.

The high-density glass fabric base copper-clad laminate of the present invention is suitable for the formation of a remarkable small-diameter penetration hole and/or via hole by irradiation, of which the wall is highly reliable, with a high-output carbon dioxide gas laser in place of a mechanical drill, and has an excellent surface smoothness and is almost free from distortion and warpage.

Ishii et al. do not disclose or teach the use of a glass fabric having a special property of the present invention, especially, having a special gas permeability.

As instructed by the Examiner at paragraph 6, Ishii et al. disclose only a preferred thickness and a weight range of a glass fabric, and absolutely do not disclose or suggest the utility of the glass fabric of the present invention.


For the foregoing reasons, it is apparent that the rejections on Ishii et al. are untenable and should be withdrawn.

No further issues remaining, allowance of this application is respectfully requested.

If the Examiner has any comments or proposals for expediting prosecution, please contact undersigned at the telephone number below.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Claims 1 to 5 have been amended as follows:

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1. (Amended) A copper-clad laminate of a [highly-elastic] glass fabric [base material]/thermosetting resin base material formed of prepreg obtained by impregnating a glass fabric base material made of a glass woven fabric having a thickness of 25 to 150 μm , a weight of 15 to 165 g/m^2 and a gas permeability of 1 to 20 $\text{cm}^3/\text{cm}^2/\text{sec}$. with a thermosetting resin composition and drying it.

2. (Amended) [A] The copper-clad laminate according to claim 1, wherein the thermosetting resin composition in the copper-clad laminate contains an insulating inorganic filler in an amount of 10 to 80 % by weight based on the above resin composition.

3. (Amended) [A] The copper-clad laminate according to claim 1, wherein the prepreg has a glass content of 25 to 70 % by weight.

4. (Amended) [A] The copper-clad laminate according to claim 1, wherein a glass fabric [base material]/thermosetting resin base material layer of the copper-clad laminate has a thickness of 30 to 150 μm .

5. (Amended) [A] The copper-clad laminate according to claim 1, wherein the thermosetting resin composition is a resin composition containing, as an essential component, a polyfunctional cyanate ester and a prepolymer of said polyfunctional cyanate ester.